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- Prof. Gene Eu (Ching Yuh) Jan, National Taipei University, Taiwan
- Prof. Fei Yuan, Ryerson University, Canada
- Prof. Zhi-Jian Xie, North Carolina A&T State University, USA

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Publication

All accepted papers after proper presentation and registration will be collected in the conference proceedings, which will be submitted and reviewed in the IEEE Xplore, Ei Compendex, Scopus, and CPCI (Web of Science) after the conference.

History

<ICICM2016|IEEE Publisher|Chengdu,China| Nov.23-25, 2016 >

Papers of ICICM2016 can be checked in IEEE Xplore and indexed by Ei Compendex and Scopus!

Electronic ISBN: 978-1-5090-2814-6 | Print ISBN: 978-1-5090-2813-9 | Print on Demand(PoD) ISBN: 978-1-5090-2815-3

<ICICM2017|IEEE Publisher|Nanjing,China| Nov.8-11,2017>

Papers of ICICM2017 can be checked in IEEE Xplore now!

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<ICICM2018|IEEE Publisher|Shanghai,China| Nov.24-26, 2018>

Topics

- Digital, Analog, Mixed Signal IC and SOC design technology
- Silicon integrated circuits and manufacturing
- Low-power, RF devices & circuits
- IC Computer-Aided –Design technology, DFM
- Silicon/germanium devices and device physics
- Interconnect, Low K, High K and other process technologies
- Unconventional and nano-electronics
- Organic semiconductor devices and technologies
- Compound semiconductor devices and circuits
- Displays, sensors and MEMS
- Semiconductor materials and material characterization
- Packaging and testing technology
- Solar cell & other devices for new energy sources
- Modeling and simulation
- Equipment technology
- Reliability
- Displays, sensors and MEMS
- Advance memories technology (Flash, FeRAM, PCM, ReRAM, MRAM etc.)

Contact

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Conference schedule

- Nov. 24, 2018—Conference Materials Collection
- Nov. 25, 2018—Keynote Speeches & papers Presentations
- Nov. 26, 2018—Peer-Reviewed Presentations

Support

- 1, Technical Support from IEEE
- 2, support from University of Electronic Science and Technology of China and Southeast University, China

